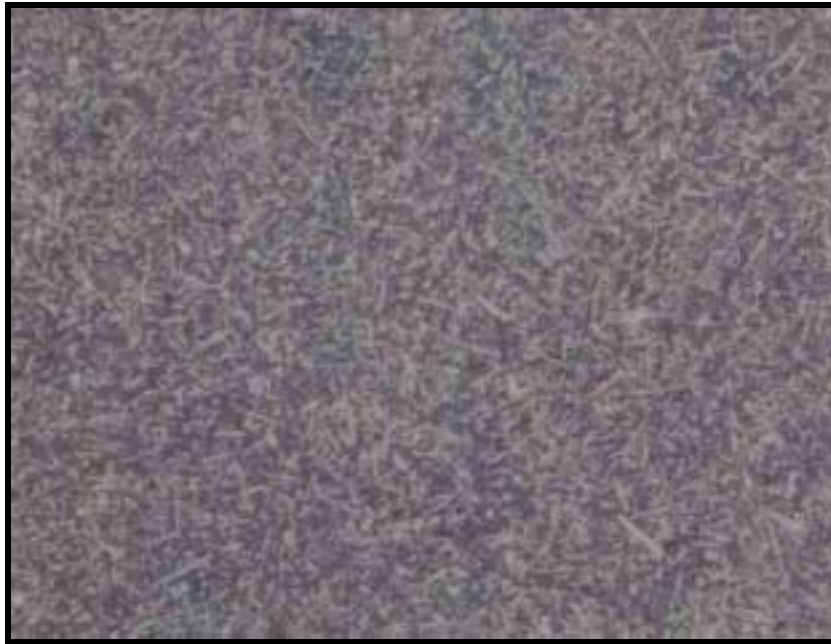


MetPrep Preparation Procedure – No 155



Kyon 2500 Alumina & SiC Whiskers

	Surface	Abrasive	Pressure		Speed – Dir	Time
			Psi	N		
Primary Grinding Stage	Fixed Diamond	40 µm MB	5	25	500 – Comp	Until Planar

	Surface	Abrasive	Pressure		Speed – Dir	Time
			Psi	N		
Additional Grinding Stages	Abracloth	15 µm (WB) PCD Diamond	5	25	250 – Comp	5 mins
	Planocloth	3 µm (WB) PCD Diamond	5	25	250 – Comp	7 mins

	Surface	Abrasive	Pressure		Speed – Dir	Time
			Psi	N		
Polishing Stage	Planocloth	0.06 µm Silco	5	25	100 – Contra	10 mins